



FEATURES:

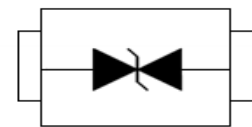
- ◇ 400 Watts peak pulse power per line ($t_P=8/20\mu s$)
- ◇ Protects one bi-directional I/O line
- ◇ Low clamping voltage
- ◇ Working voltage:24V
- ◇ Low leakage current
- ◇ RoHS compliant



SOD-323

MAIN APPLICATIONS

- ◇ Cell phone handsets and accessories
- ◇ Microprocessor based equipment
- ◇ Personal digital assistants (PDA's)
- ◇ Notebooks, desktops, and servers
- ◇ Portable instrumentation



Pin Configuration

PROTECTION SOLUTION TO MEET

- ◇ IEC61000-4-2 (ESD) $\pm 30kV$ (air), $\pm 30kV$ (contact)
- ◇ IEC61000-4-4 (EFT) 40A (5/50ns)
- ◇ IEC61000-4-5 (Lightning) 8A(8/20 μs)

MECHANICAL CHARACTERISTICS

- ◇ SOD-323 package
- ◇ Molding compound flammability rating : UL 94V-0
- ◇ Weight 5 milligrams (approximate)
- ◇ Quantity per reel : 3,000pcs
- ◇ Lead finish : lead free
- ◇ Marking code: 24B

ABSOLUTE MAXIMUM RATINGS (T_A=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20μs waveform	P _{PP}	400	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	+/- 30 +/- 30	kV
Lead soldering temperature	T _L	260 (10 sec.)	°C
Operating junction temperature range	T _J	-55 to +125	°C
Storage temperature range	T _{STG}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS (T_A=25°C)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V _{RWM}				24	V
Reverse breakdown voltage	V _{BR}	I _T =1mA	26.7			V
Reverse leakage current	I _R	V _{RWM} =24V			1	μA
Clamping voltage (I/O pin to Ground)	V _C	I _{PP} =1A, t _p =8/20μs			40	V
		I _{PP} =8A, t _p =8/20μs			50	V
Junction capacitance	C _J	V _{RWM} =0V, f=1MHz		30	35	pF

RATINGS AND V-I CHARACTERISTICS CURVES (T_A=25°C, unless otherwise noted)

FIG.1: V- I curve characteristics (Bi-directional)

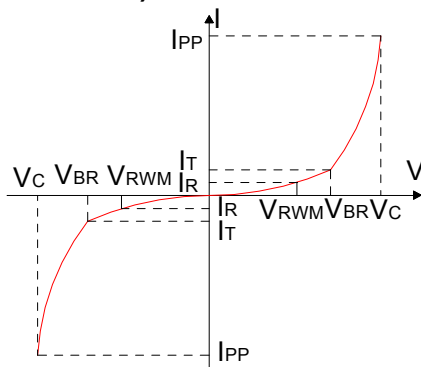


FIG.2: Pulse waveform (8/20μs)

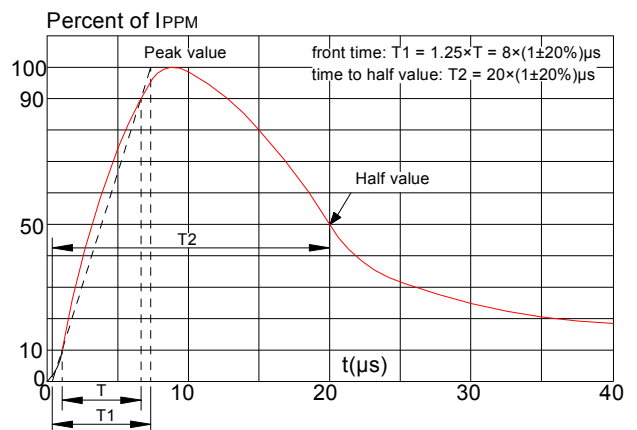


FIG.3: Pulse derating curve

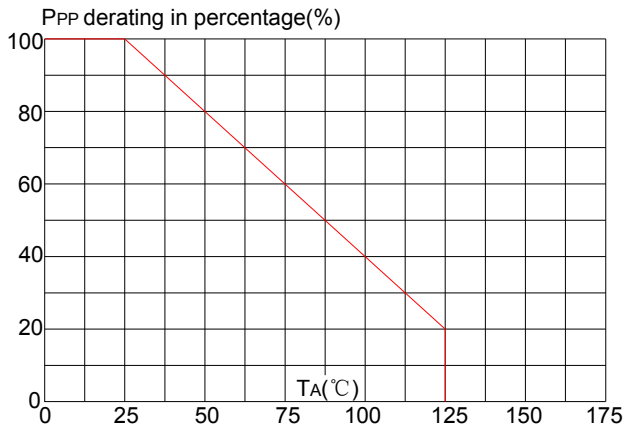
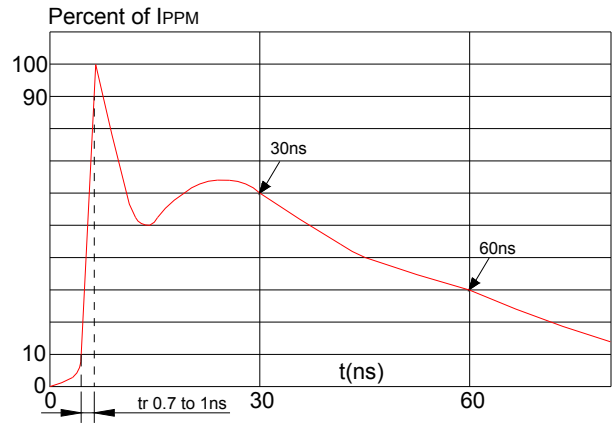
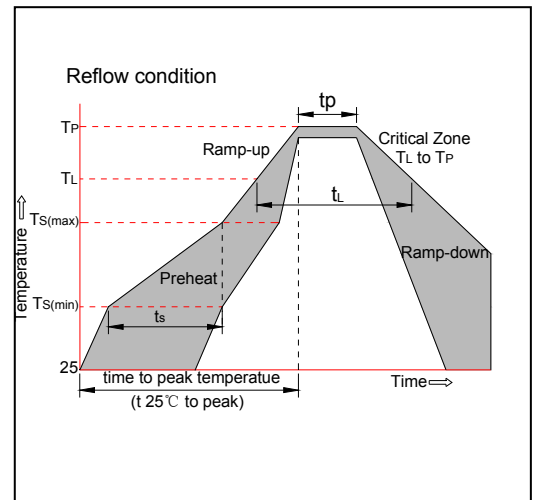


FIG.4: ESD clamping (30kV contact)

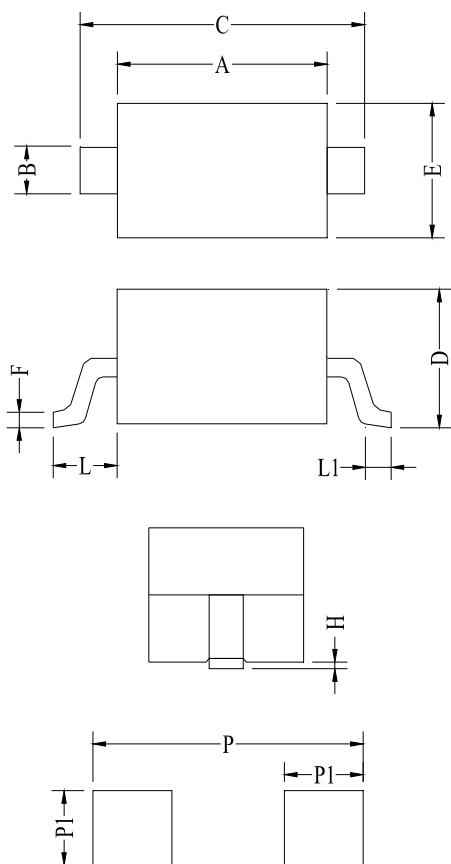


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquidus)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C



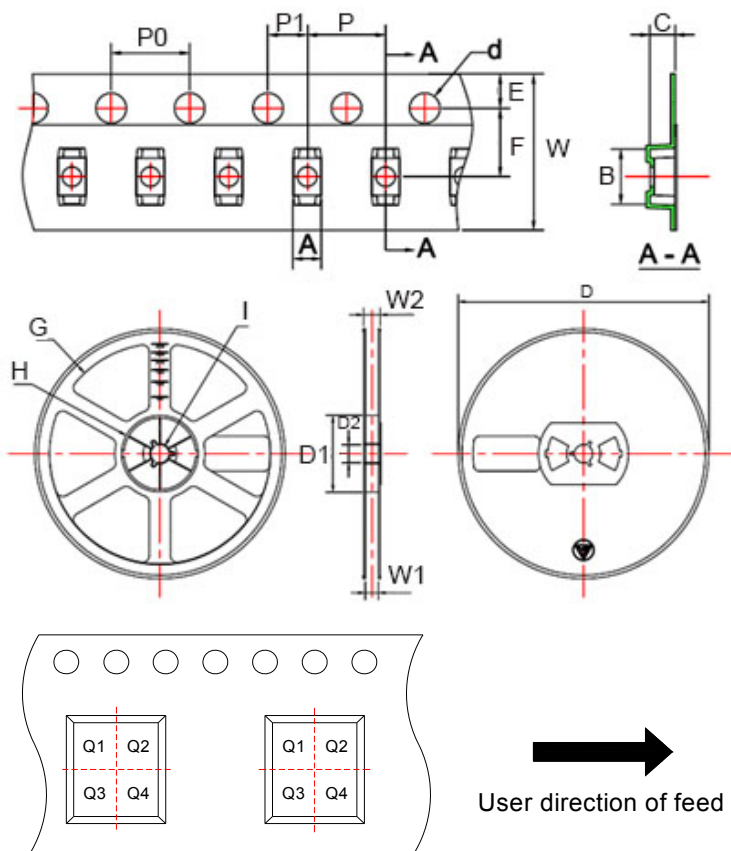
PACKAGE MECHANICAL DATA



Land Pattern

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
A	1.60	1.70	1.80	0.063	0.067	0.071
B	0.25	0.32	0.40	0.010	0.013	0.016
C	2.30	2.60	2.80	0.091	0.102	0.110
D	0.80	0.95	1.10	0.031	0.037	0.043
E	1.20	1.30	1.40	0.047	0.051	0.055
F	0.08	0.13	0.18	0.003	0.005	0.007
L	0.475REF			0.019REF		
L1	0.25	0.33	0.40	0.010	0.013	0.016
H	0.00	0.06	0.14	0.000	0.002	0.006
P	3.00			0.118		
P1	0.80			0.031		

TAPE AND REEL INFORMATION-SOD-323



Pin 1 quadrant:Q1&Q2

Packaging description:

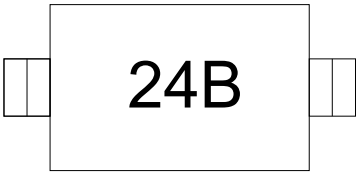
SOD-323 parts are shipped in tape. The carrier tape is made from a dissipative(carbon filled) polycarbonate resin. The cover tape is a multilayer film(heat activated adhesive in nature)primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. The reels are blue in color and made of recyclable plastic.

Symbol	Millimeters	Inches
	Typ	Typ
A	1.46	0.057
B	2.90	0.114
C	1.25	0.049
d	ø1.50	ø0.059
E	1.75	0.069
F	3.50	0.138
P0	4.00	0.157
P	4.00	0.157
P1	2.00	0.079
W	8.00	0.315
D	ø178.0	ø7.008
D1	54.40	2.142
D2	13.00	0.512
G	R78.0	R3.071
H	R25.60	R1.008
I	R6.50	R0.256
W1	9.50	0.374
W2	12.30	0.484

ORDERING INFORMATION

PART No.	PACKAGE TYPE	QUANTITY(PCS) REEL	DESCRIPTION
JEB24D3	SOD-323	3,000	7 inch reel pack

MARKING CODE

Part Number	Marking Code
JEB24D3	

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